



## Call for Papers

**Accepted Papers Will Be  
Collected in IEEE Xplore!**

IMPACT 2021 Conference, organized by IEEE-EPS-Taipei, iMAPS-Taiwan, ITRI and TPCA, is the largest gathering of PCB and packaging professionals in Taiwan. This year will be held on Oct. 20th -22nd at Taipei Nangang Exhibition Center, in conjunction with TPCA Show 2021. For grasping the latest trend, the symposium this year highlights the theme "IMPACT on 5G+". As the rapid growth of 5G coverage over the world, the 5G commercial network enables an array of revolutionary technologies such as IoT, artificial intelligence (AI), edge computing and wearable devices. Given the foundational infrastructure is advancing along with technologies, 5G brings faster speed and connectivity to those using it.

IMPACT 2021 looks at the cutting-edge technological applications. With the increasing amount of data collected and leverage machine learning and artificial intelligence, may achieve a breakthrough in terms of high security and privacy-preservation, and increased efficiency.

IMPACT 2021 will arrange plenary speeches, special sessions, industrial sessions, invited talks, and outstanding paper and poster presentations. Meanwhile, this conference keeps collaborating with international organizations such as ICEP、JIEP from Japan, KAIST from South Korea, and iNEMI from USA in this year's gathering.

**[Date] : Oct 20 (Wed)-22(Fri), 2021**  
**[Venue] : Taipei Nangang Exhibition Center**  
**[Theme] : IMPACT on 5G+**

**[Exhibition] : TPCA Show、TAITRONICS、Laser & Photonics Taiwan、OPTO TAIWAN、AloT Taiwan**  
**[On-line Submission] : [www.impact.org.tw](http://www.impact.org.tw)**

### IMPORTANT DATE

| Item  | Date      | Remark   |
|---|-----------|--|
| Abstract Submission Deadline (Camera-ready Version) | June 18   | 400-500 words, 1-2 pages<br>Submit on-line <a href="http://www.impact.org.tw">www.impact.org.tw</a>              |
| Abstract Acceptance Notification                    | July 14   | Notice sent via email  |
| Advanced Program Online                             | August 18 | Advanced program announcement  |
| Full Paper Submission (Camera-ready Version)        | August 31 | 4 pages including figures and tables.<br>Submitting on-line through conference website with IEEE copyright forms |

### SCOPE OF PAPER SOLICITED

| Packaging  | PCB  |
|--|--|
| P1. Advanced Packaging Technologies                  | B1. Advanced and Green Materials and Process   |
| P2. Power Electronics Packaging                      | B2. Test, Quality, AOI, Inspection and Reliability   |
| P3. Heterogeneous Integration                        | B3. HDI Technology(Fine and ultra fine line technology for Rigid、Flex、Rigid/Flex and IC substrate) |
| P4. Wearable Technologies                            | B4. Electroplating and Electrochemical Processing Technology                                       |
| P5. Interconnections & Nanotechnology                | B5. Smart Manufacturing and Automation   |
| P6. Modeling, Simulation & Design                    |  |
| P7. Thermal Management                               |  |
| P8. Advanced Sensor & Microsystems Technology (MST)  |  |
| P9. Advanced Materials, Automatic Process & Assembly |  |
| P10. Emerging Systems Packaging Technologies         |  |

\* Papers relevant with the above scopes are encouraged to submit but NOT limited to.  
\* Conference authority keeps the right to finalize session arrangement.  
\* Authors of accepted papers including oral presentation and posters should register before the deadline; please be noted that un-registered (paid) papers will be removed from the symposium program.  
\* The secretariat reserves the right to modify the agenda.

### PAPER AWARD

Outstanding Paper Award will be elected by IMPACT Technical Program Committee from student and industrial papers respectively. The paper awardees will be announced and honored next year.

### SPONSOR

IMPACT2021 sponsors can improve the corporate image, enhance professional development, create networking opportunities and enjoy exclusive benefits. There are multiple sponsorship packages for you to choose!

### CONTACT WINDOW

IMPACT 2021 Secretariat:  
Taiwan Printed Circuit Association (TPCA)  
Tel: +886-3-3815659  
#407 Cindy #404 Sophia #406 Vivi  
Fax: +886-3-3815150  
Email: [service@impact.org.tw](mailto:service@impact.org.tw)  
[http:// www.impact.org.tw](http://www.impact.org.tw)



[www.impact.org.tw](http://www.impact.org.tw)

